


# MATERIAL DECLARATION SHEET



|                 |                        |     |          |   |
|-----------------|------------------------|-----|----------|---|
| Material Number | CD0201-T2.0LC          |     |          |  |
| Product Line    | Semiconductor Products |     |          |   |
| Compliance Date | 2020/6/5               |     |          |   |
| RoHS Compliant  | <b>Yes</b>             | MSL | <b>1</b> |   |

| No. | Construction Element(subpart) | Homogeneous Material | Material weight [mg] | Homogeneous Material\ Substances   | CASRN if applicable | Materials Mass % | Material Mass % of total unit wt. | Subpart mass of total wt. (%) |
|-----|-------------------------------|----------------------|----------------------|------------------------------------|---------------------|------------------|-----------------------------------|-------------------------------|
| 1   | Wafer                         | Silicon              | 0.0100               | Silicon                            | 7440-21-3           | 100.00%          | 3.63%                             | 3.63%                         |
| 2   | Lead Frame                    | Noble metal          | 0.1540               | Tin                                | 7440-31-5           | 0.26%            | 0.15%                             | 55.94%                        |
|     |                               |                      |                      | Zinc                               | 7440-66-6           | 0.23%            | 0.13%                             |                               |
|     |                               |                      |                      | Chromium                           | 7440-47-3           | 0.26%            | 0.15%                             |                               |
|     |                               |                      |                      | Copper                             | 7440-50-8           | 98.30%           | 54.98%                            |                               |
|     |                               |                      |                      | Nickel                             | 7440-02-0           | 0.90%            | 0.50%                             |                               |
|     |                               |                      |                      | Palladium                          | 7440-05-3           | 0.03%            | 0.02%                             |                               |
|     |                               |                      |                      | Gold                               | 7440-57-5           | 0.02%            | 0.01%                             |                               |
| 3   | Epoxy                         | Polymer              | 0.0081               | Aluminium oxide - non fibrous form | 1344-28-1           | 42.50%           | 1.25%                             | 2.94%                         |
|     |                               |                      |                      | Epoxy Resin                        | Proprietary         | 37.50%           | 1.10%                             |                               |

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|   |               |             |        |                              |              |        |        |        |
|---|---------------|-------------|--------|------------------------------|--------------|--------|--------|--------|
|   |               |             |        | Epoxy resin                  | Proprietary  | 12.50% | 0.37%  |        |
|   |               |             |        | Dapsone                      | 80-08-0      | 6.25%  | 0.18%  |        |
|   |               |             |        | 3-Aminopropyltriethoxysilane | 919-30-2     | 1.25%  | 0.04%  |        |
| 4 | Wire          | Noble metal | 0.0032 | Aurum                        | 7440-57-5    | 99.99% | 1.16%  | 1.16%  |
|   |               |             |        | Misc not to declare          | -            | 0.01%  | 0.00%  |        |
| 5 | Mold Compound | Polymer     | 0.1000 | Solid Epoxy Resin -1         | Trade secret | 1.00%  | 0.36%  | 36.33% |
|   |               |             |        | Solid Epoxy Resin -2         | Trade secret | 5.00%  | 1.82%  |        |
|   |               |             |        | Phenol Resin                 | Trade secret | 2.00%  | 0.73%  |        |
|   |               |             |        | Carbon Black                 | 1333-86-4    | 0.50%  | 0.18%  |        |
|   |               |             |        | Metal Hydroxide              | Trade secret | 1.00%  | 0.36%  |        |
|   |               |             |        | Amorphous silica             | 60676-86-0   | 88.00% | 31.97% |        |
|   |               |             |        | Crystalline silica           | 14808-60-7   | 2.50%  | 0.91%  |        |

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|              |           |
|--------------|-----------|
| Total weight | 0.2753 mg |
|--------------|-----------|

**This Document was updated on: 2020/6/5**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.